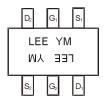


#### **Marking Information**



LEE = Product Type Marking Code YM = Date Code Marking Y or  $\underline{Y}$  = Year (ex: I = 2021) M or  $\underline{M}$  = Month (ex: 9 = September)

Date Code Key

Year	2016		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	D		- 1	J	K	L	М	N	0	Р	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

# Maximum Ratings (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	60	V
Gate-Source Voltage		V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	Steady State	I <sub>D</sub>	350 290	mA
Maximum Continuous Body Diode Forward Currer	Is	350	mA	

# Thermal Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		P <sub>D</sub>	320	mW
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R <sub>θJA</sub>	400	°C/W
Total Power Dissipation (Note 6)		P <sub>D</sub>	410	mW
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>θJA</sub>	312	°C/W
Operating and Storage Temperature Range		T <sub>J,</sub> T <sub>STG</sub>	-55 to +150	°C

Notes:

<sup>5.</sup> Device mounted on FR-4 PCB, with minimum recommended pad layout 6. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.



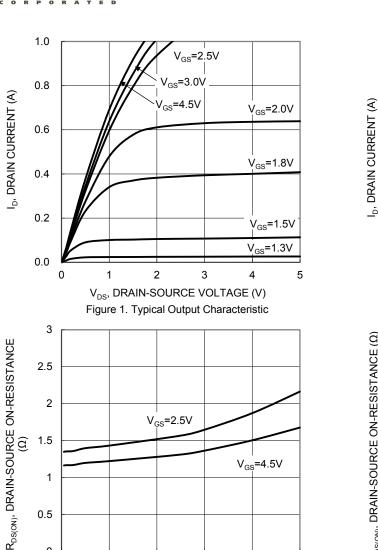
# Electrical Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1.0	μA	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±10	μA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5		1.0	>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 250μA	
			1.2	2.0		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.1A	
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	_	1.4	2.5	Ω	$V_{GS} = 2.5V, I_D = 0.05A$	
			1.8	3.0		V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 0.05A	
Forward Transconductance	Y <sub>fs</sub>	_	1.8	_	S	V <sub>DS</sub> =10V, I <sub>D</sub> = 0.2A	
Diode Forward Voltage	V <sub>SD</sub>	_	8.0	1.3	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 115mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>iss</sub>	_	32	_	рF		
Output Capacitance	Coss	_	3.9	_	pF	$V_{DS} = 30V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	2.4	_	pF	1 - 1.00012	
Gate Resistance	Rg	_	101	_	Ω	$f = 1MHz$ , $V_{GS} = 0V$ , $V_{DS} = 0V$	
Total Gate Charge	Qg	_	0.5	_	nC		
Gate-Source Charge	Q <sub>gs</sub>	_	0.09	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 250 \text{mA}$	
Gate-Drain Charge	Q <sub>gd</sub>	_	0.09	_	nC	ID - 250IIIA	
Turn-On Delay Time	t <sub>D(on)</sub>	_	2.4	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	2.5	_	ns	V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V,	
Turn-Off Delay Time	t <sub>D(off)</sub>	_	22.6	_	ns	$R_G = 25\Omega$ , $I_D = 200mA$	
Turn-Off Fall Time	t <sub>F</sub>	_	12.5	_	ns		

Notes: 7. Short duration pulse test used to minimize self-heating effect.

<sup>8.</sup> Guaranteed by design. Not subject to product testing.





I<sub>D</sub>, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

0.6

8.0

0.4

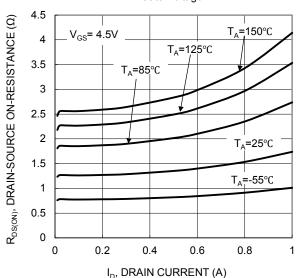
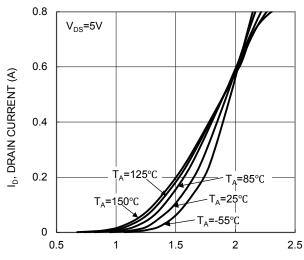
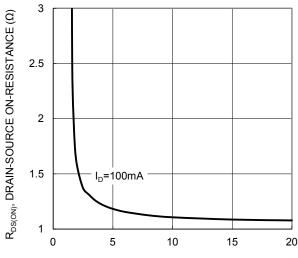


Figure 5. Typical On-Resistance vs. Drain Current and Temperature



 $V_{GS}$ , GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic



V<sub>GS</sub>, GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic

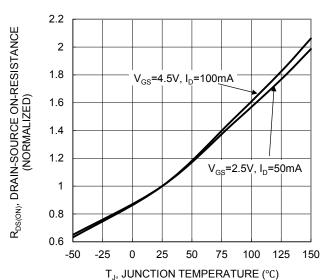


Figure 6. On-Resistance Variation with Junction Temperature

0.5

0 0

0.2





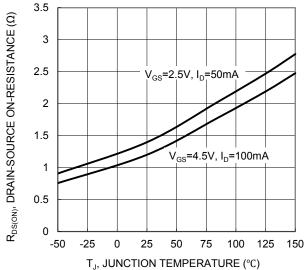
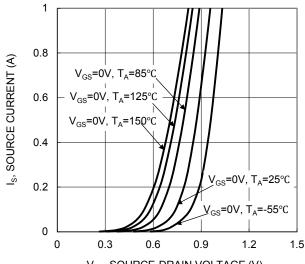
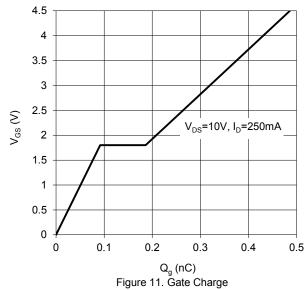


Figure 7. On-Resistance Variation with Junction Temperature



 $V_{SD}$ , SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current



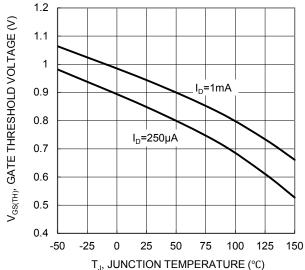
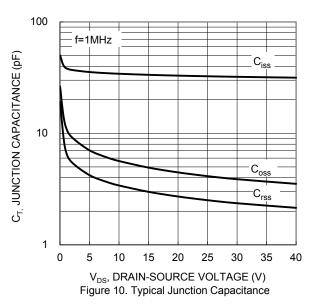


Figure 8. Gate Threshold Variation vs. Junction Temperature



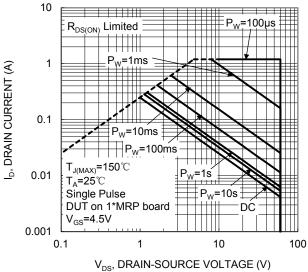


Figure 12. SOA, Safe Operation Area



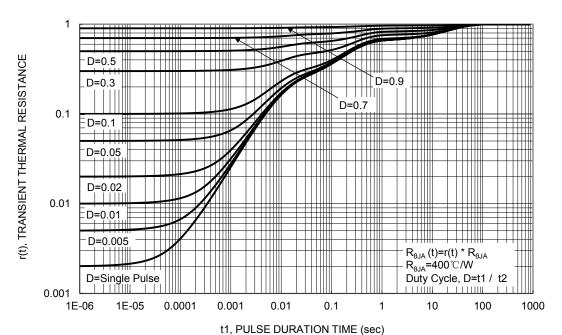


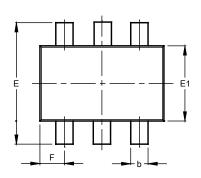
Figure 13. Transient Thermal Resistance

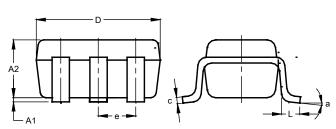


# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT363 (Standard)



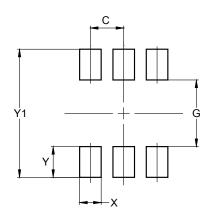


SOT363 (Standard)							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.80	1.00	0.90				
b	0.10	0.35	0.225				
C	0.08	0.22	0.15				
D	1.80	2.20	2.00				
Е	2.00	2.45	2.225				
E1	1.15	1.35	1.25				
е			0.65				
F	0.25	0.45	0.35				
L	0.25	0.46	0.355				
а	0°	8°					
All Dimensions in mm							

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT363 (Standard)



Dimensions	Value (in mm)				
Dillieligions					
С	0.650				
G	1.300				
Х	0.420				
Y	0.600				
Y1	2.500				



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